U.S. DEPARTMENT OF COMMERCE

SON-2401 1	02099087  Patent and Trademark Office
To the Honorable Commissioner of Patents and Trademarks	s: Please record the attached original documents or copy thereof.
Name of conveying party(ies)	2. Name and address of receiving party(ies)
(1) Seiryu Takayama (2) Ryo Ando (3) Takao MARUYAMA Additional name(s) of conveying party(ies) attached No.	Name: SONY CORPORATION Internal Address:
3. Nature of conveyance:	Street Address: 7-35 KITASHINAGAWA 6-CHOME SHINAGAWA-KU
□ Merger	City: TOKYO, JAPAN
☐ Security Agreement ☐ Change of Name  Execution Date:  (1) May 7, 2002 (2) May 9, 2002, (3) May 10, 2002	Additional name(s) & address(es) attached ☐ Yes ☒ No
Application number(s) or patent number(s):  If the document is being filed together with a new application.	10,145727 cation, the execution date of the application (1) 5/7/02 (2) 5/09/02 (3) 5/10/02
Name and address of party to whom correspondence cordocument should be mailed:	6. Total number of applications and patents involved: 1
Name: Ronald P. Kananen, Esq.	7. Total fee (37 CFR 3.41)\$ <b>40.00</b>
Internal Address: RADER, FISHMAN & GRAUER	☐ Enclosed
Suite 501	Authorized to be charged to Deposit Account
Street Address: 1233 20 <sup>th</sup> Street, NW  City: Washington, D.C. Zip: 20036  DO NOT USE THIS SPACE	8. Deposit account number:  18-0013  (Attach duplicate copy of this page if paying by deposit account)
9 Statement and signature.	Aformation is true and correct and any attached copy is a true copy of the original  May 16, 2002  Signature  Date

**PATENT REEL: 012902 FRAME: 0410** 

SON-	2/1	$\sim$	1
2011-	24	v	1

Docket Number:

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in DISK DRIVE APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

would conflict with this assignment and sale.	, , , , , , , , , , , , , , , , , , , ,
And I hereby authorize and request my attorney(s) of record in this at this application in the spaces that follow: Serial Number:	application to insert the serial number and filing date of Filing Date:
This assignment executed on the dates indicated below.	
SEIRYU TAKAYAMA	Execution date of U.S. Patent Application
Name of first or sole inventor	
KANAGAWA, JAPAN	
Residence of first or sole inventor	May 7, 2002
Secrya Jakayama	Date of this assignment

Signature of first or sole inventor

RYO ANDO	
Name of second inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN	
Residence of second inventor	
Signature of second inventor	May 9, 2002
Signature of second inventor	Date of this assignment
TAKAO MARUYAMA	
Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of third inventor	
Signature of third inventor	May 10. 2002  Date of this assignment
Signature of third inventor	Date of this assignment
Name of fourth inventor	Execution date of U.S. Patent Application
Residence of fourth inventor	
Signature of fourth inventor	Date of this assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	Date of this assignment
Signature of fifth inventor	Date of this assignment
Signature of fifth inventor	

PATENT
RECORDED: 05/16/2002 REEL: 012902 FRAME: 0412